



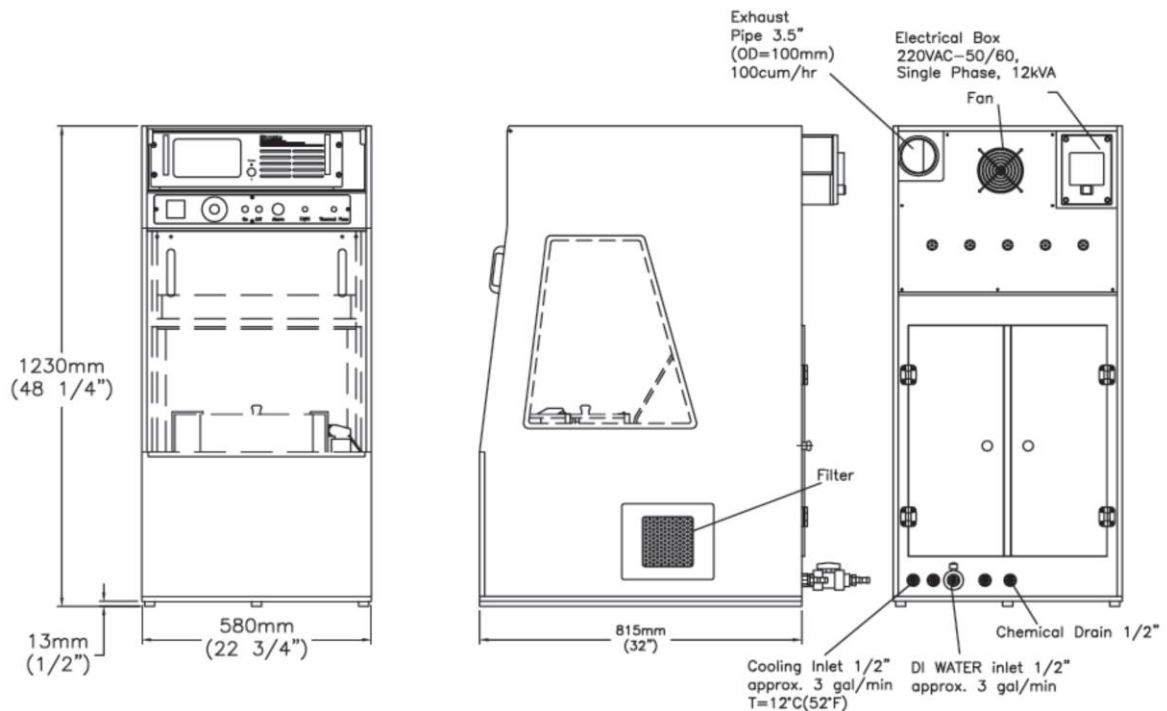
PRODUCT DATASHEET

PMT-16 – Precious Metal Wafer Electroplating System



Features

- Small footprint
- Compact, single cell
- High flow rate
- Efficient filtration
- Easy process maintenance
- Easy operator interface
- Precision digital microprocessor control
- **Precious Metals Applications:**
 - Gold, Gold alloy
 - Silver
 - Tungsten, Tungsten Alloy
 - Palladium, Palladium Alloy
 - Rhodium, Rhodium Alloy





PRODUCT DATASHEET

PMT-16 – Precious Metal Wafer Electroplating System

Specifications	
Construction:	Polypropylene
Dimensions:	Width 22 3/4" (580mm)
	Height 50" (1300mm)
	Depth 32" (815mm)
Wafer Dimension Standard:	101.6, 152.3 and 203.2mm
Total Solution Volume:	12 gal. (45 liters)
Heaters:	0.5 kW
Cooling:	Teflon cooling coil
Cells:	1
Pump:	1/15 hp.
Rectifier:	Standard 27A, 24VDC Standard (optional available)
Filtration:	1 Stage 5 micron DOE 10"
Flow:	5-lpm max (adjustable) per cell
Alarm	High level and low level protection
Instrumentation:	
Temperature Controller:	± 1 degree C Dual setpoint
Utilities:	
Electrical	200/220VAC, 1 Phase, 6kVA, 50/60Hz
DI Water:	>17 Meg-Ohm, 1/2" 45 psi, 4 gpm on demand
Cooling:	11 lph, Pressure 45-60 psi, Temp. = 12°C (52°F)
Exhaust	400 CFM 3 1/2" Outside Diameter

